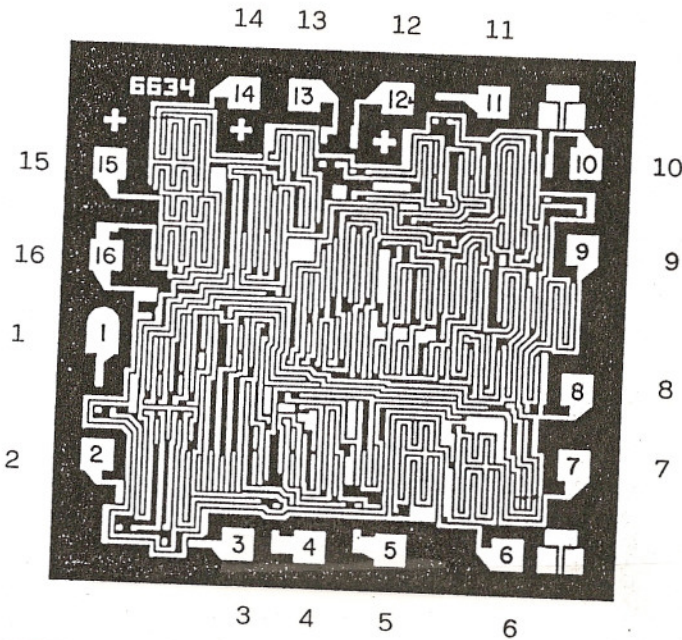




Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>PAD NO</u>	<u>FUNCTIONS</u>
1	D4
2	D5
3	D6
4	D7
5	E _I
6	Q2
7	Q1
8	VSS
9	Q0
10	D0
11	D1
12	D2
13	D3
14	GS
15	E _O
16	VDD

Topside Metal:
Backside:
Backside Potential:
Mask Ref:
Bond Pads (Mils):

APPROVED BY:
MFG: RCA

DIE SIZE (Mils): 76 X 73
THICKNESS:

DATE: 3/13/00
P/N: CD4532

DG 10.1.2
 Rev A 3-4-99